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Substitute Form PTO-1449 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-855001	Application No.		
Information Disclosure Statement by Applicant		Applicant Valery M. Dubin			
	neets if necessary)	Filing Date September 24, 2003	Group Art Unit		

U.S. Patent Documents							
Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
MA	AA	6,325,909	12/04/2001	Li et al.			
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Foreign Patent Documents or Published Foreign Patent Applications								
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Initial	I D	Number	Date	Patent Office	Class	Subclass	Yes	No
	AL							
	AM							
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Other Documents (include Author, Title, Date, and Place of Publication)				
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BWB	AQ	Frank G. Shi, "Advanced IC Interconnect and Packaging: Materials and Processing Issues", Project Report 2000-01 for MICRO Project 00-088		
1	AR	Jamin Ling et al., "Direct Bump-on-Copper Process for Flip Chip Technologies", Kulicke & Soffa – Flip Chip Division, Agere Systems Inc.		
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Examiner Signature	Date Considered				
KJW///V	13/14/09				
EXAMINER: Infilals citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with					
next communication to applicant.	Cubalituta Dindonus Fort (DTO 4440)				